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**(54) THICK-FILM PHOTORESIST LAYER LAMINATE, PRODUCTION METHOD OF THICK-FILM RESIST PATTERN AND PRODUCTION METHOD OF CONNECTION TERMINAL**

**(57)Abstract:**

**PROBLEM TO BE SOLVED:** To provide a means by which a resist composition can sensitively react to form a high precision resist pattern in a thick-film photoresist layer used in manufacture of connection terminal and so on.

**SOLUTION:** The resist pattern is formed by using the thick-film photoresist layer laminate which features that a substrate (a) and the thick-film photoresist layer (b) containing the resin whose alkali solubility is changed by the action of acid and an acid generating agent are laminated via a shielding layer (c) obstructing the contact between the substrate (a) and the thick-film photoresist layer (b), and the connection terminal is formed by using the same.

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